



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS723GW		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000990168						
<b>Package</b>		PG-DSO-14-37		<b>Weight*</b>		144.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.803	4.02	4.02	40191	40191
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		104	
	non noble metal	zinc	7440-66-6	0.060	0.04		418	
	non noble metal	iron	7439-89-6	1.207	0.84		8359	
wire	non noble metal	copper	7440-50-8	49.007	33.94	34.83	339423	348304
	noble metal	gold	7440-57-5	1.105	0.77	0.77	7651	7651
	encapsulation	organic material	carbon black	1333-86-4	0.167	0.12		1156
plastics		epoxy resin	-	7.675	5.32		53159	
	inorganic material	silicondioxide	60676-86-0	75.585	52.34	57.78	523504	577819
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8492	8492
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7132	7132
glue	plastics	epoxy resin	-	0.263	0.18		1822	
	noble metal	silver	7440-22-4	1.240	0.86	1.04	8589	10411
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com